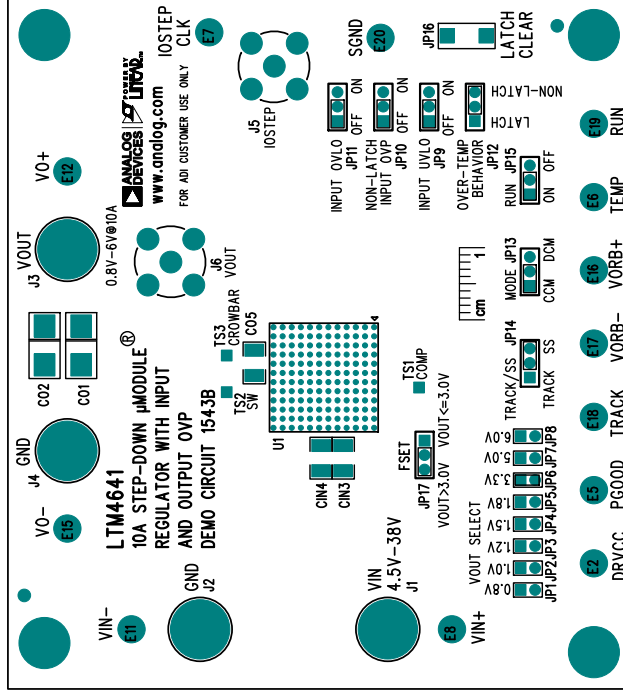
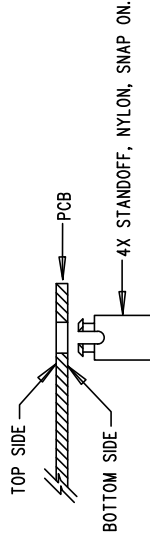



REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
1	2	PRODUCTION	YAN L.	5-9-19

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE; REFLOW SOLDER TOP SIDE SMD.
3. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
5. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
6. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
7. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
8. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
9. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS				#330 MCCARTHY BLVD MILPITAS, CA 95035 WWW.LINEAR.COM FAX: CUSTOMER USE ONLY	
PCB DES.	HZ				
APP ENG.	YAN L.				
		TITLE: TOP ASSEMBLY DRAWING® 10A STEP-DOWN μMODULE® REGULATOR WITH INPUT AND OUTPUT OVP			
		SIZE	IC NO.	LTM4641EY	REV.
		N/A		DEMO CIRCUIT	1543B 2
SCALE = NONE		FILL NAME:		DC1543B-1 PCB	
				SHT 1 OF 2	